

# PATENT ABSTRACTS OF JAPAN

(11)Publication number : 61-156780

(43)Date of publication of application : 16.07.1986

(51)Int.Cl.

H01L 33/00  
H01L 27/15

(21)Application number : 59-274621

(71)Applicant : TOSHIBA CORP

(22)Date of filing : 28.12.1984

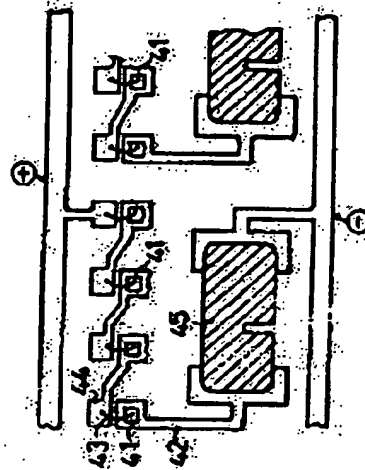
(72)Inventor : NAGASAWA YUTAKA

## (54) MANUFACTURE OF LIGHT-EMITTING ELEMENT ALIGNMENT ASSEMBLY BODY

(57)Abstract:

**PURPOSE:** To uniformize the luminous intensity of each light-emitting element by a method wherein resistors are formed on the insulating substrate, the light-emitting elements are die-mounted on the substrate and after an electrode wiring is performed, the resistivity of each resistor is adjusted in a state that the light-emitting elements are being actuated.

**CONSTITUTION:** A paste for resistance is printed on the resistor disposition parts on an insulating substrate 51 and a sintering is performed. Whereby resistors 45 are preformed. Then, LEDs 41 are respectively connection-fixed on the prescribed wiring pattern parts on the substrate 51 and a wire-bonding is performed on other wiring pattern parts and the LEDs 41 using fine metal wires 43 to form the circuit. After that, adjustment of the resistivity of each resistor 45 preformed is performed so that the luminous intensity of the total of the LEDs 41 becomes a constant value in a state that the LEDs 41 are being actuated. By this way, the control of the resistivity of the light-emitting element alignment assembly body becomes possible. As a result, the LED array having no dispersion of the luminous intensity on the optical axis can be obtained.



## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]